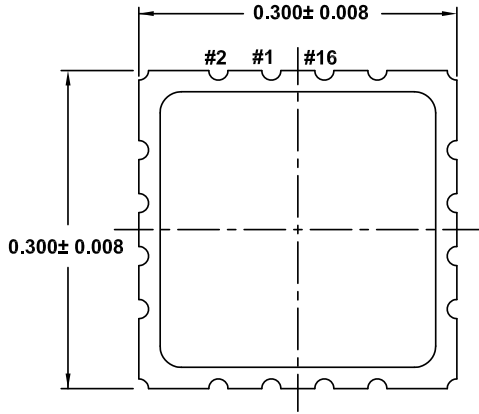


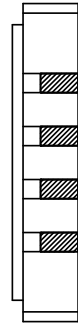
# Ceramic Packages for Integrated Circuits

## Package Outline Drawing

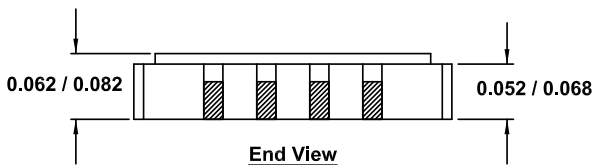
J16.A  
 16 Pad Ceramic Leadless Chip Carrier (CLCC)  
 Rev 0, 1/20



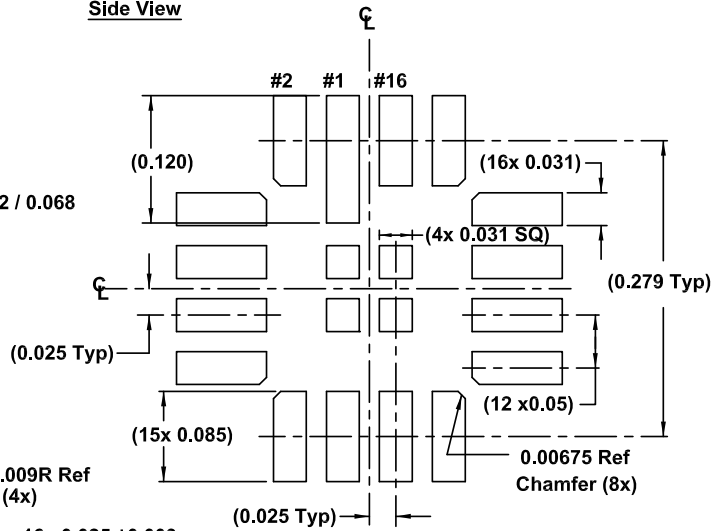
Top View



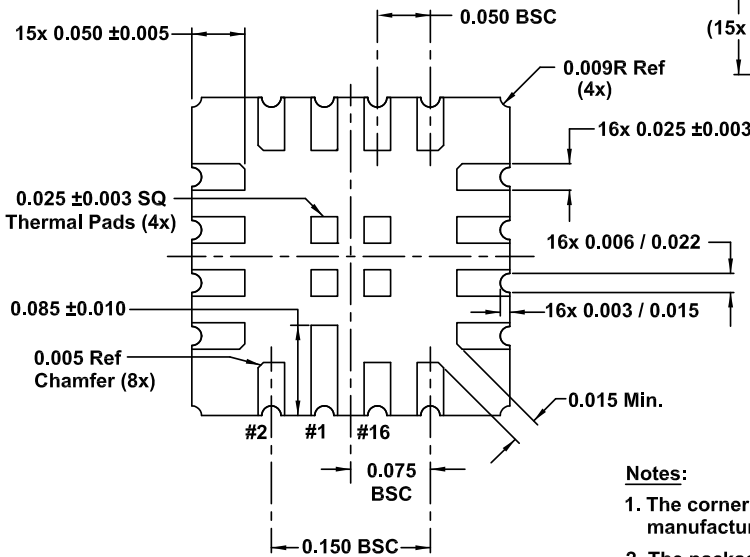
Side View



End View



Recommended Land Pattern



Bottom View

**Notes:**

1. The corner shape (such as radius, or chamfer) may vary at the manufacturers option from that shown on the drawing.
2. The package thickness dimension is the package height before being solder dipped.
3. Dimensions are in inches.  
Dimensioning in ( ) for reference only.
4. Package Is also compliant to MIL-STD-1835 CQCC1-N16 (C-1).